Method for singulating a group of semiconductor packages and comprising a plastic molded body.

Abstract

Method for singulating a group of semiconductor packages (100) comprising a plastic molded body (104). The singulation of the semiconductor packages (100) is effected along a predetermined separation area (S), wherein, in the predetermined separation area (S), a metallic layer (106) extending over at least a partial section of the predetermined separation area (S) has to be cut through in addition to a plastic layer consisting of the material of the molded body (104). The method comprises the following steps: making a groove into the predetermined separation area (S) of the semiconductor packages (100) by laser engraving, wherein at least a part of the metallic layer (106) extending in the predetermined singulation area (S) is removed, and subsequent separation of the semiconductor packages (100) by means of a mechanical sawing cut along the predetermined separation area (S).

Fig. 3